BTX Barebone systems
to build quiet and cool computers!

Win more contracts with super silent, cool & small BTX systems!

£125 / 150€

Includes all BTX components:
- Chassis & foot stand,
- Fujitsu Siemens Mainboard,
- Cooling system,
- 275W Power supply,
- Power cord,
- 2 x SATA cable,
- Manual & DVD.

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- United Kingdom
- France
- Germany
- Poland
- Hong Kong
- Japan
- Malaysia

Features:
- Micro BTX Tower or Desktop
- Silent: A single fan efficiently controlled by PWM technology.
- Cool: New mainboard design for an outstanding ventilation.
- Small: BTX makes small chassis compatible with newest technologies: PCI Express, SATA.
- Energy saving: Environment friendly system.
- Unique mainboard features for a durable, stable, simple & secure system.
- Screwless drives for an easy installation.
- 2 Front USB and HD audio ports.
- Passed EMC & Thermal tests by Intel.

Options:
- Riser Card.
- Alternative chassis design available.
- Alternative motherboard with Q33 and Q35 Intel chipsets available (Mini Qty: 40pcs).
- Various CPU available (Mini Qty: 40pcs).

Not included in this package: (Standard ATX components)
- SATA drives,
- RAM, CPU,
- Operating System.

Specifications:	Micro BTX Tower	Micro BTX Desktop
Drive space:	2 x 5.25", 2 x 3.5", 2 x HDD	1 x 5.25", 1 x 3.5", 2 x HDD
Mainboard:	Micro BTX Fujitsu Mainboard D3011-A	
Power Supply Unit:	300W PS2 type	275W CFX type
Ventilation:	1 unique 90mm case / CPU fan controlled by PWM technology. No other fan required.	
Packing (12kg / item):	Uk pallet: 40pcs, Euro Pallet: 28pcs Bulk Pack: 20, 24, 28, 44 or 52 Pcs	Uk pallet: 56pcs, Euro Pallet: 44pcs Bulk Pack: 36, 44 or 80pcs

Mainboard:	Fujitsu D3011-A
Processors:	Intel Core 2 Duo, Core 2 Quad, Pentium Dual Core, Celeron Dual Core, Celeron.
Chipset:	Intel® 43
Board Size:	µBTX 10,5" x 9.95" (266.7x264.2mm)
Memory:	DDR3 1066 SDRAM
Features:	Intel AMT 3.5 technology, Graphics, PCI Express Generation 2, Multichannel Audio, USB 2.0, Intel GBE LAN, Serial ATA II, Trusted Platform Module V1.2. Board prepared for EuP.

Silent fan, System Guard, Silent Drives, Recovery BIOS, Desk Update, Multi Boot, HDD Password. |

OEM container & European pallet orders available. Alternative designs, CPUs & mainboards available.
Evercase UK is part of the KM Groups, in association with Fujitsu Siemens mainboards & Fire Bull power supply y units.

BTX Technology
Outstanding thermal and acoustic solution

BTX Technology:
BTX (Balanced Technology Extended) is a form factor for PC motherboards designed to replace the aging ATX technology. It has been designed to bring latest technologies that need more power and produce more heat into small form factor housings.
The revolutionary BTX technology has not died. It has not been popular with small and medium system integrators due to the difficulty to find BTX components. However, due to its outstanding benefits, A-brand professional PC providers such as **Fujitsu Siemens Computers, Dell** and **HP** have fully integrated BTX into their systems and will continue to do so.

The outstanding acoustic and thermal improvements achieved by BTX technology are due to a new layout of the motherboard. The CPU is cooled down directly from the fresh air blown in by the front fan, and all components are strategically situated and orientated to optimize the front to back air flow path. This can reduce the temperature by 5 to 10 degrees compared to the ATX system. The only fan required is the massive CPU cooler. The result is a dramatic reduction of noise, heat, power consumption and consequently system size. We now provide all essential BTX components, so like many of our customers, win more tenders and contracts by using the outstanding benefits of BTX as unique selling points.

ATX challenge	How BTX addresses the problem
Limited scalability: ATX does not scale well into small form factor (SFF) designs. Core layout in Flex ATX exceedingly difficult. Custom SFF designs are generally expensive and often exclusionary. Performance silicon often excluded.	**Improved scalability**: System ingredients with standard interface definitions in a broader range of sizes. Two standard thermal Module designs. Three standard board sizes with common core area design. Pico BTX: 1 expansion slot. Micro BTX: 4 expansion slots. BTX: 7 expansion slots. LFX12V and CFX12V added to the existing standard power supply portfolio to support small form factor PCs.
Expensive to cool: Increasing system thermal demands can require substantial R&D investment in new heatsink and voltage regulation technologies and extensive chassis modifications.	**Superior Thermal Environment**: High power components use the same in-line, high velocity, low temperature airflow. Above and below motherboard airflow helps improve voltage regulation and socket capability.
Increasing noise: Increasing system thermal demands generally require more and noisier fans.	**Superior Acoustic Performance**: Only two fans required even in high performance configurations. Thermal module fan and PSU fan create and manage simplified system airflow. Lower impedance and high velocity, low temperature air allows lower fan speed.
Motherboard design complexity: Routing and component placement in ATX becoming increasing complex: Core routing area saturated, processor power delivery placement constrained, ICH-tp-1/0 routing lengh, MCH-to-memory routing imbalance.	**Improved Motherboard Design**: More room for power delivery and rear panel I/O. Balanced memory and localized I/O routing.
Limited support for heavy heatsinks: ATX platforms limited to 450 gram CPU heatsink mass.	**Improved Structural Integrity:** 100% increase in allowable CPU heatsink mass (900g). Single, reusable ingredient (Support and Retention Module) used in all system sizes**.**
Increasing cost to keep up with thermal requirements: ATX power delivery, power dissipation, and motherboard design liabilities increase cost: new heatsink technologies, new voltage regulation technologies and increased component count, chassis modifications.	**Improved Cost Structure**: Low temperature, high velocity airflow allows simpler, less costly heatsink technologies. Standard ingredients replace custom ingredients for compact system designs.

<u>We offer</u>:
-All essential BTX components: BTX chassis, Cooling system,
Power supply unit & motherboard.
-OEM container & European pallet orders available.
-High quality ATX / BTX convertible chassis.
-Fujitsu Siemens motherboards made in Europe.
-Customized design, colour and logo printing.
-Alternative chassis designs available.
-Alternative mainboards available (Mini Order: 40pcs).
-Various CPU at discounted prices available (Mini Order: 40pcs).
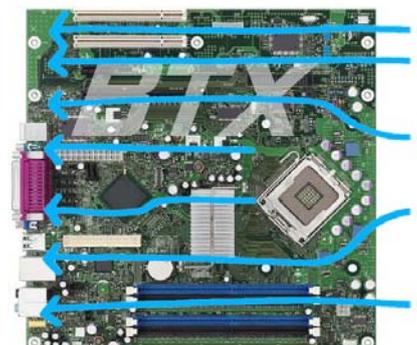*-Bulk or single packaging.*

BTX Components.
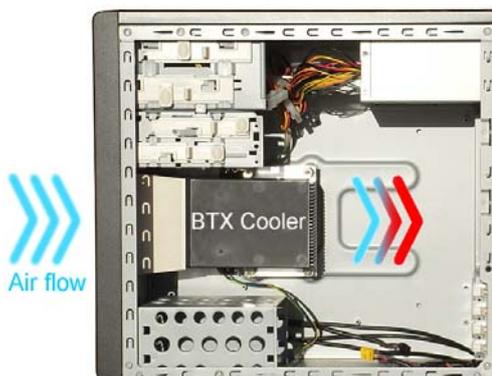
BTX cooling system.

ATX obstructed airflow.

BTX improved airflow.